

1. SCOPE

This specification shall cover the characteristics of 1-port SAW resonator with used for remote-control security.

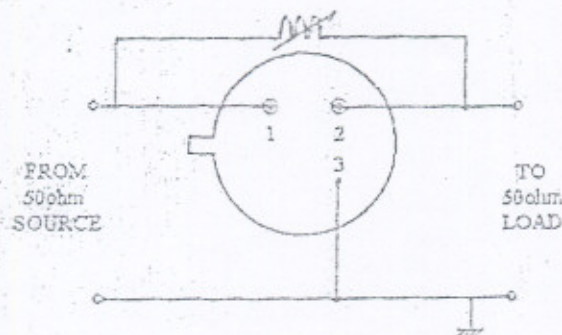
2. ELECTRICAL SPECIFICATION

DC Voltage VDC	10V
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-40°C to +85°C
Storage temperature	-45°C to +85°C
RF Power Dissipation	0dBm

Electronic Characteristics

Item	Units	Minimum	Typical	Maximum
Center Frequency	MHz	433.845	433.920	433.995
Insertion Loss	dB		1.8	2.5
Quality Factor Unload Q			12,800	
.50 Ω Loaded Q			2,000	
Temperature	Turnover Temperature	°C	39	
Stability	Turnover Frequency	KHz	$f_0 \pm 2.7$	
	Freq-temp Coefficient	ppm/°C	0.037	
Frequency Aging	ppm/yr		± 10	
DC Insulation Resistance	M Ω	1.0		
RF Equivalent RLC Model	Motional Resistance R1	Ω	18	26
	Motional Inductance L1	μ H	86	
	Motional Capacitance C1	pF	1.5	
Pin 1 to Pin 2 Static Capacitance	pF	1.7	2.0	2.3
Transducer Static Capacitance	pF		1.9	

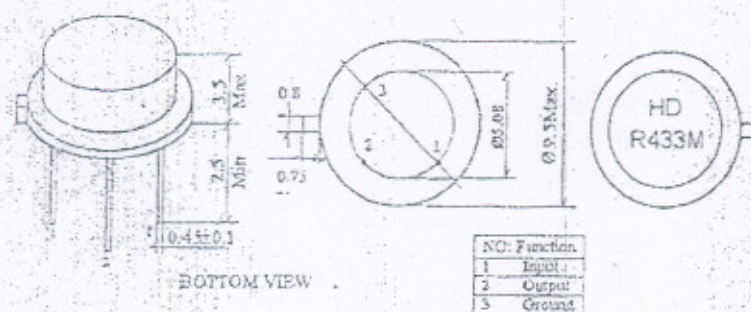
3. TEST CIRCUIT



4. DIMENSION

P/N: 050-433924-113 PAGE 3 OF 4

MODEL: GENERAL



5. ENVIRONMENTAL CHARACTERISTICS

5-1 High temperature exposure

Subject the device to +80°C for 96 hours. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall fulfill the specifications in table 1.

5-2 Moisture

Keep the device at 40°C and 95% rh for 96 hours. then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall fulfill the specifications in table 1.

5-3 Low temperature exposure

Subject the device to -20°C for 96 hours. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall fulfill the specifications in table 1.

5-4 Temperature cycling

Subject the device to a low temperature of -55°C for 30 minutes. Following by a high temperature of +85°C for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in table 1.

5-5 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 270°C ± 10°C for 10 ± 1 sec. Then release the device into the room conditions for 1 to 2 hours. The Filter shall meet the specifications in table 1.

5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 30cm 3 times. the device shall fulfill the specifications in table 1.

5-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with

the amplitude of 1.5 mm at 10 to 55 Hz. The device shall meet the specifications in table 1.

5-8 Lead fatigue

5-8-1 Pulling test

device shall satisfy all the initial Characteristics.

5-8-2 Bending test

Lead shall be subject to withstand against 90°C bending in the direction of thickness. This operation shall be done toward both direction. The device shall show no evidence of damage and shall satisfy all the initial electrical characteristics.

6. REMARK

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

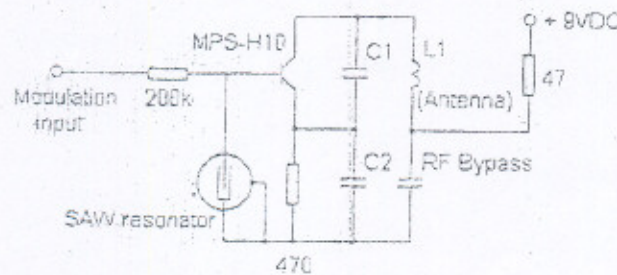
Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.

7. Typical Application Circuit

Typical low-power Transmitter Application



Typical Local Oscillator Application

